

### AMENDMENTS TO THE CLAIMS

Following is a listing of all claims in the present application, which listing supersedes all previously presented claims:

#### Listing of Claims:

1. (Previously Presented) A structure for providing resilient interconnections in a wafer level package, comprising a conductive pad that directly overlays an air space formed in a dielectric layer, wherein at least a portion of the air space formed in the dielectric layer extends laterally beyond the conductive pad and wherein a perimeter of the conductive pad directly overlies both regions of the air space formed in the dielectric layer and regions of the dielectric layer.
2. (Original) The structure as claimed in claim 1, wherein the air space comprises a geometric structure having a plurality of perimeter interconnect support structures for the conductive pad.
3. (Original) The structure as claimed in claim 2, wherein at least one perimeter interconnect support structure also supports a conductive line electrically connected to the conductive pad.
4. (Original) The structure as claimed in claim 3, wherein the conductive line is a metal wire.

5. (Original) The structure as claimed in claim 1, wherein a major axis of the air space is radial to a center of the wafer level package.

6. (Original) The structure as claimed in claim 1, wherein a major axis of the air space is not radial to a center of the wafer level package.

7-20. (Canceled).

21. (Previously Presented) The structure as claimed in claim 1, wherein the conductive pad comprises a bond pad.

22. (Previously Presented) The structure as claimed in claim 1, wherein the air space formed in the dielectric layer comprises a plurality of perimeter support structures that partially underlie the conductive pad.

23. (Previously Presented) The structure as claimed in claim 22, wherein the air space formed in the dielectric layer comprises a plurality of perimeter dielectric support structures that partially underlie the conductive pad.

24. (Previously Presented) A structure for providing resilient interconnections in a wafer level package, comprising a conductive pad that directly overlays an air space, wherein at least a portion of the air space extends laterally beyond the conductive pad and wherein the air space comprises a geometric structure having a plurality of perimeter interconnect support structures for the conductive pad.

25. (Previously Presented) The structure as claimed in claim 24, wherein at least one perimeter interconnect support structure also supports a conductive line electrically connected to the conductive pad.

26. (Previously Presented) The structure as claimed in claim 25, wherein the conductive line is a metal wire.

27. (Previously Presented) The structure as claimed in claim 24, wherein a major axis of the air space is radial to a center of the wafer level package.

28. (Previously Presented) The structure as claimed in claim 24, wherein a major axis of the air space is not radial to a center of the wafer level package.

29. (Previously Presented) A structure for providing resilient interconnections in a wafer level package, comprising a conductive pad that directly overlays an air space, wherein at least a portion of the air space extends laterally beyond the conductive pad, and wherein a major axis of the air space is radial to a center of the wafer level package.

30. (Canceled).